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June 14, 2005

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject:

Serial No.	10/685,872	10/15/02
M.S. LIN ET AL		
"POST PASSIVATION INTERCONNECTION SCHEMES ON TOP OF THE IC CHIPS"		
Group Art Unit: 2822	KEVIN M. PICARDAT	

RESPONSE TO OFFICE ACTION


Dear Sir:

In response to the Office Action dated January 14, 2005, please amend the above-identified application for patent as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on June 14, 2005.

Stephen B. Ackerman, Reg. No. 37,761

Signature 
Date 6/14/05

Amendments to the Specification begin on page 3 of this paper.

Amendments to the Claims are reflected in the listing of the Claims which begins on page 4 of this paper.

Amendments to the Drawings begin on page 12 of this paper and include an attached replacement sheet.

Remarks/Arguments begin on page 13 of this paper.

An Appendix including amended drawing figures is attached following page 16 of this paper.